

# FH3400A

## N-Channel Enhancement Mode MOSFET

### Description

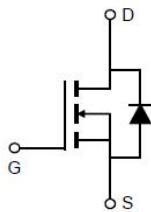
The FH3400A uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and high density cell Design for ultra low on resistance. This device is suitable for use as a load switch or in PWM applications.

### Application

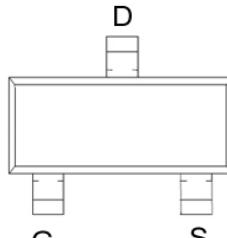
- ◆ PWM applications
- ◆ Load switch

### General Features

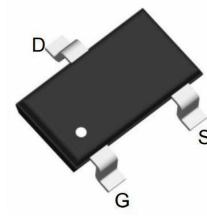
- ◆  $V_{DS} = 30V$ ,  $I_D = 6.5A$
- ◆  $R_{DS(ON)}(\text{Typ.}) = 17m\Omega$  @  $V_{GS} = 10V$
- ◆  $R_{DS(ON)}(\text{Typ.}) = 18m\Omega$  @  $V_{GS} = 4.5V$
- ◆  $R_{DS(ON)}(\text{Typ.}) = 24m\Omega$  @  $V_{GS} = 2.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ Fast Switching



Schematic diagram



Marking and Pin Assignment



SOT-23 top view

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	30	V
Gate-source voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	6.5	A
Pulsed Drain Current (Note 3)	$I_{DM}$	26	A
Drain-source Diode forward current (Note 1)	$I_S$	2.5	A
Maximum power dissipation	$P_D$	1.25	W
Operating junction Temperature range	$T_j$	-55 – 150	°C

### Thermal Characteristics

Thermal Resistance junction-to ambient (Note 3)	R <sub>th JA</sub>	100	°C/W
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## ■ Electrical Characteristics ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Static</b>						
Drain-source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	30	35		V
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	0.65		1.2	V
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 12\text{V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{\text{DS}}^0$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 6.0\text{A}$		17	21	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 5.0\text{A}$		18	22	
		$V_{\text{GS}} = 2.5\text{V}, I_{\text{D}} = 4.0\text{A}$		24	29	
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}} = 5\text{V}, I_{\text{D}} = 5.0\text{A}$		11		S
Diode Forward Voltage <b>(Note 2)</b>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{S}} = 2.5\text{A}$			1.2	V
Diode Forward Current <b>(Note 1)</b>	$I_{\text{S}}$				2.5	A
<b>Dynamic</b>						
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 3\text{A}$		7.0		nC
Gate-Source Charge	$Q_{\text{gs}}$			1.3		
Gate-Drain Charge	$Q_{\text{gd}}$			18		
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		760		pF
Output Capacitance	$C_{\text{oss}}$			88		
Reverse Transfer Capacitance	$C_{\text{rss}}$			67		
<b>Switching</b>						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DS}} = 15\text{V}, R_{\text{L}} = 15\Omega, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega, I_{\text{D}} = 1\text{A}$		9		nS
Rise Time	$t_r$			3.3		
Turn-Off Delay Time	$t_{\text{d(off)}}$			29.3		
Fall-Time	$t_f$			3.4		

- Note:**
1. Mounted on FR4 board,  $t \leq 10\text{sec}$ .
  2. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
  3. Repetitive Rating: Pulse width limited by maximum junction temperature.

## Typical Performance Characteristics

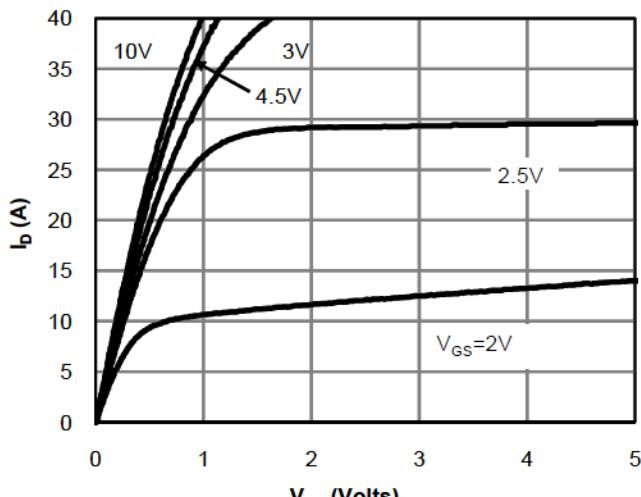


Fig 1: On-Region Characteristics (Note E)

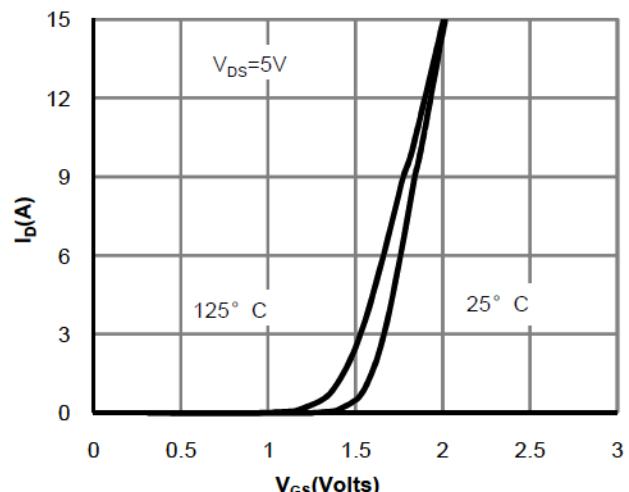


Figure 2: Transfer Characteristics (Note E)

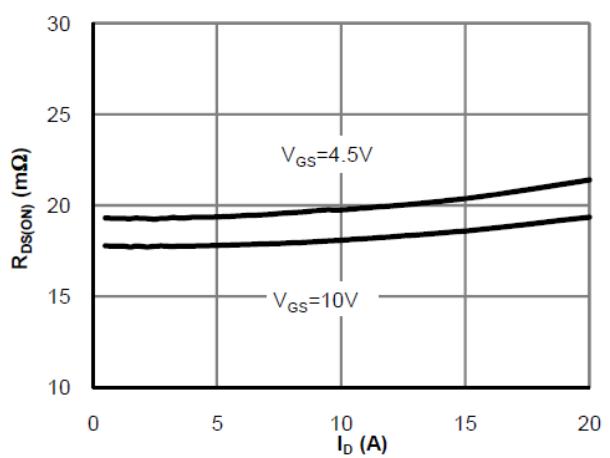


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

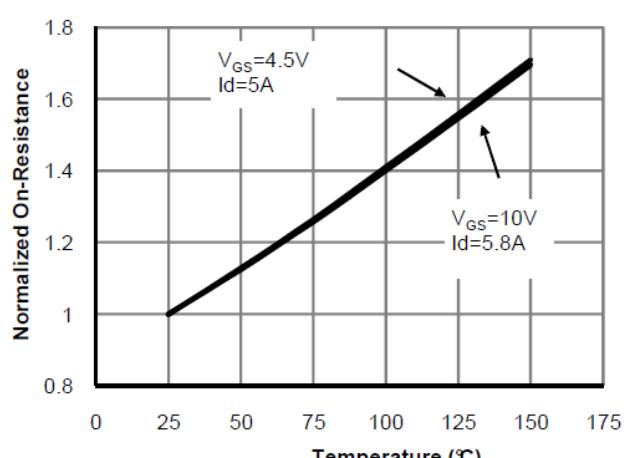


Figure 4: On-Resistance vs. Junction Temperature (Note E)

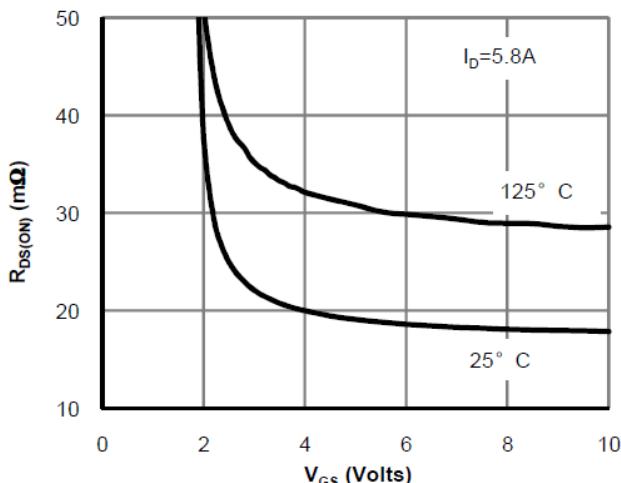


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

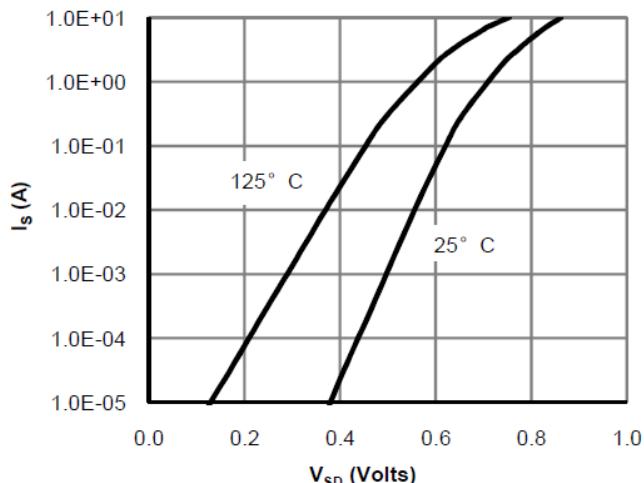


Figure 6: Body-Diode Characteristics (Note E)

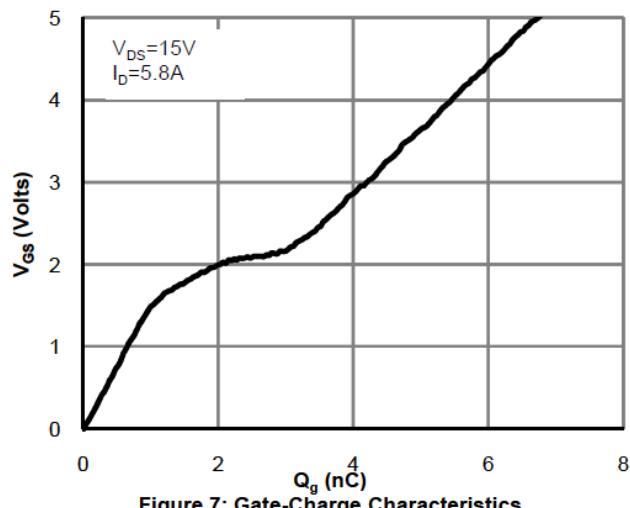


Figure 7: Gate-Charge Characteristics

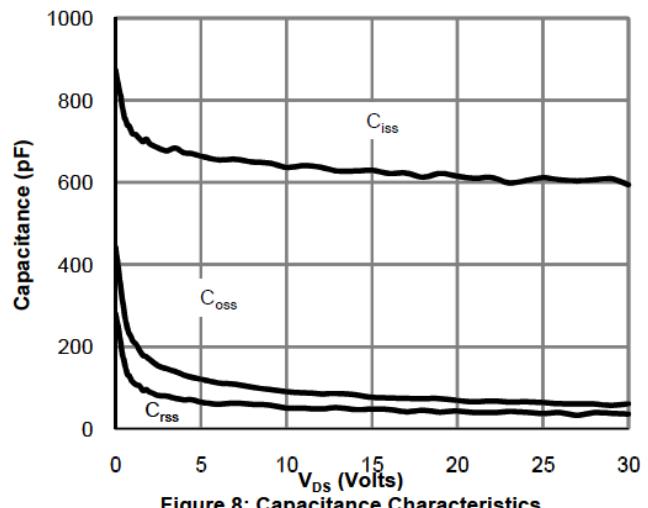


Figure 8: Capacitance Characteristics

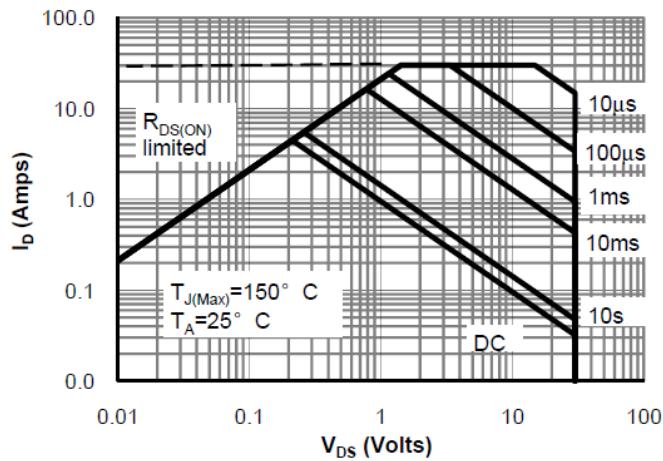


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

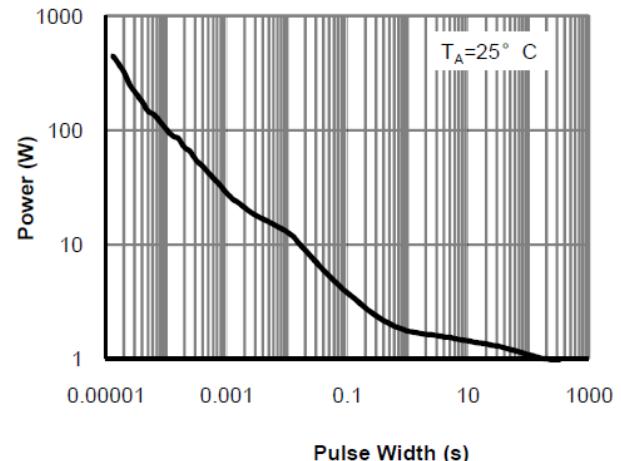


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

## ■ Typical Electrical and Thermal Characteristics

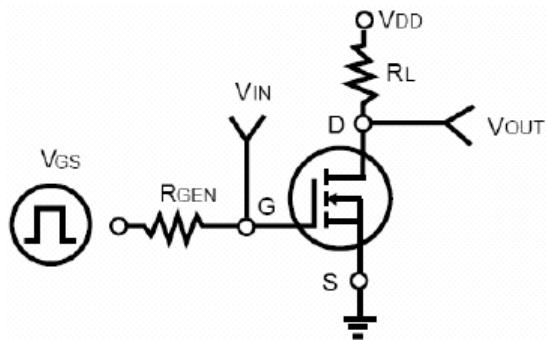


Figure 1: Switching Test Circuit

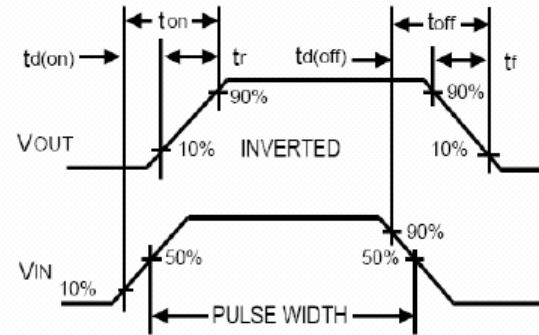


Figure 2: Switching Waveforms

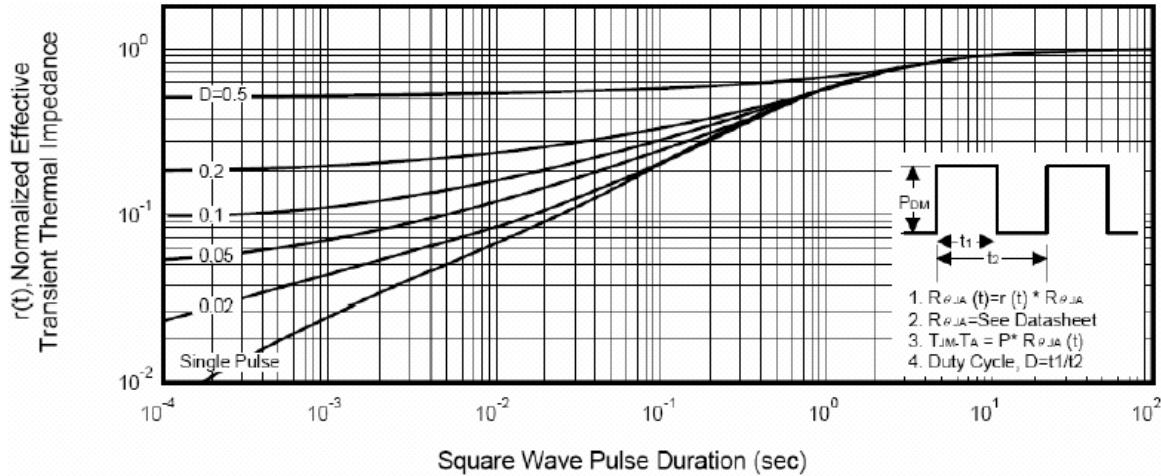
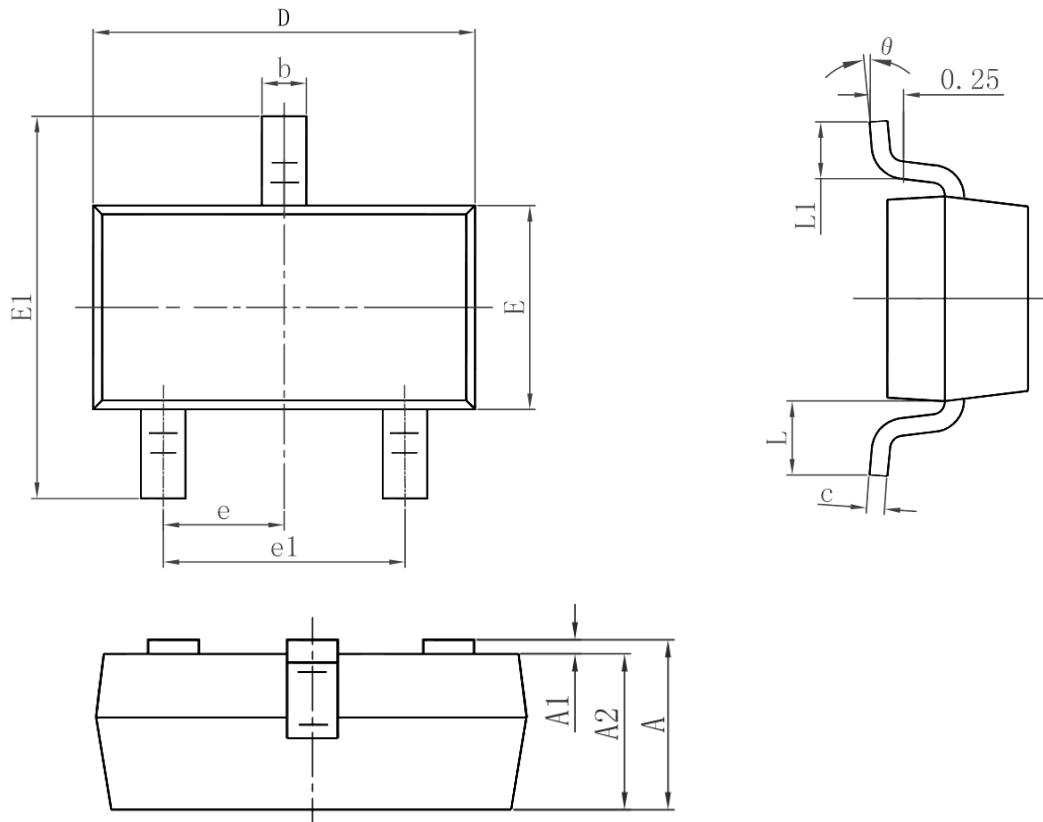


Figure 3: Normalized Maximum Transient Thermal Impedance

**Package Information : SOT-23**

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP.	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF.	
L1	0.300	0.500	0.012	0.020
theta	0°	8°	0°	8°